



Ampoc Far East Co., Ltd



Ampoc Far-East Co., Ltd.

Investor Conference



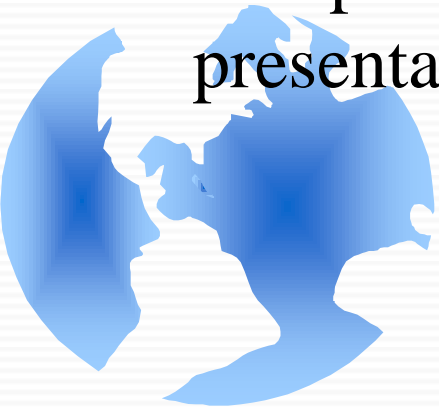
2018/05/23





DISCLOSURE

For the convenience of readers, this presentation has been translated into English from the original Chinese version. If there is any conflict between the English version and the original Chinese version or any difference in the interpretation of the two versions, the Chinese-language presentation shall prevail.





Ampoc Far East Co., Ltd

• Ampoc Profile

• Company History

• Products Introduction and

Application

• Financial Information

• Future Outlook





Ampoc Far East Co., Ltd

Company Profile

Company : AMPOC Far-East Co., Ltd.

Address : 17F., No.171, Sung-Teh Road,
Taipei, Taiwan

Tel : (02) 2726-2220

Fax : (02) 2726-2227

E-mail : 1service@ampoc.com.tw

Responsible Person :

Chairman & C.E.O., Mr. Ronald S. Su

Executive VP & C.O.O., Mr. Alden Chiao

Since : November 1, 1980

Paid-up Capital : NT\$ 1,144 Million

Employee : 280



董事長兼總經理
蘇勝義先生



Company History

AMPOC's History



- 2006/12 • Ampec merged Yang Shin Investment Co., Ltd which Ampec owned 100%.
- 2002/01 • Ampec was approved to list on the Taiwan Stock Exchange, Stock Code: 2493
- 2001/06 • Stock dividend was issued, resulting in total capital of NT\$905 million.
- 2000/10 • Paid-in capital was increased to NT\$73.7 million.
- 1999/12 • Ampec merged with TTCM and issued additional 21,107,000 shares, paid-in capital increased to NT\$57.1 million.
- 1998/12 • Ampec was approved as public company.
Ampec was engaged in capitalization of NT\$10.2 million, paid-in capital increased to NT\$30 million
- 1998/03 • Ampec established the inspection lab. with precision instruments to enhance our service quality.
- 1997/03 • Ampec purchased the office which located at 17F, No.171, Sung-Teh Rd., Sinyi District, Taipei.
- 1987/05 • TCM in Japan which was a master manufacturer of PCB Wet Process established TTCM in CHUNG-LI industrial zone, Taiwan. Ampec invested in TTCM and obtained the sole global distribution agreement except in Japan.
- 1980/11 • Ampec was founded in Taipei with initially registered capital of NT\$1 million.



Applications and Products Introduction

□ Applications

- Semiconductor (Front-end)
- Advanced Packaging Process
- MEMS

• Products Introduction

- Ampoc Wing Vertical System
- Conventional Horizontal System
- Test Equipment for Products of Inertial Component



Ampoc Far East Co., Ltd



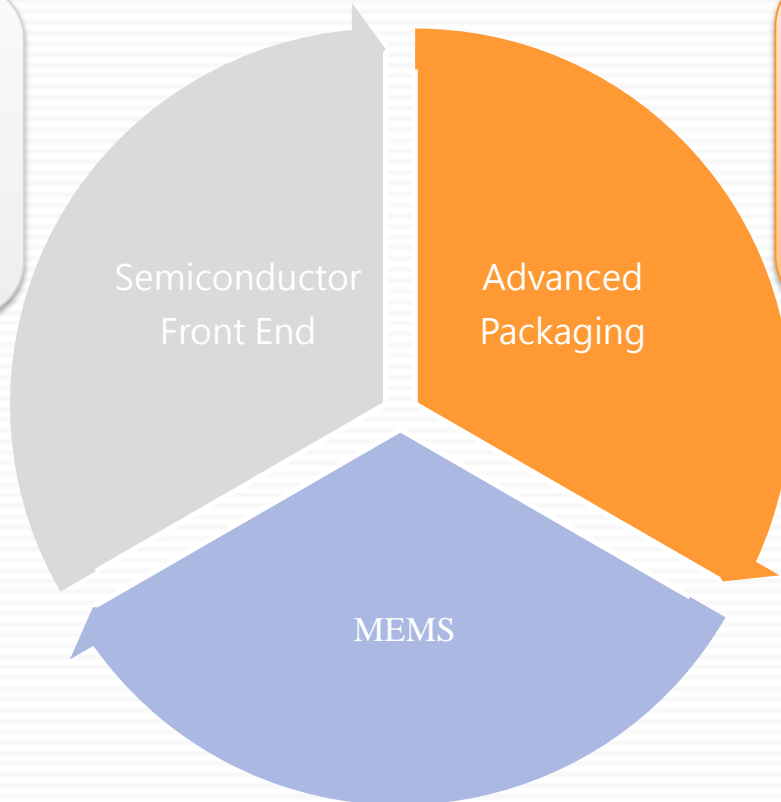
Applications





Applications- Core Development Strategies

- ✓ Plating chemicals for flip chip bump
- ✓ 3D-IC, FOWLP interconnection high-speed plating
- ✓ UBM layer high selective etching chemicals
- ✓ High resolution photoresist
- ✓ Hard mask

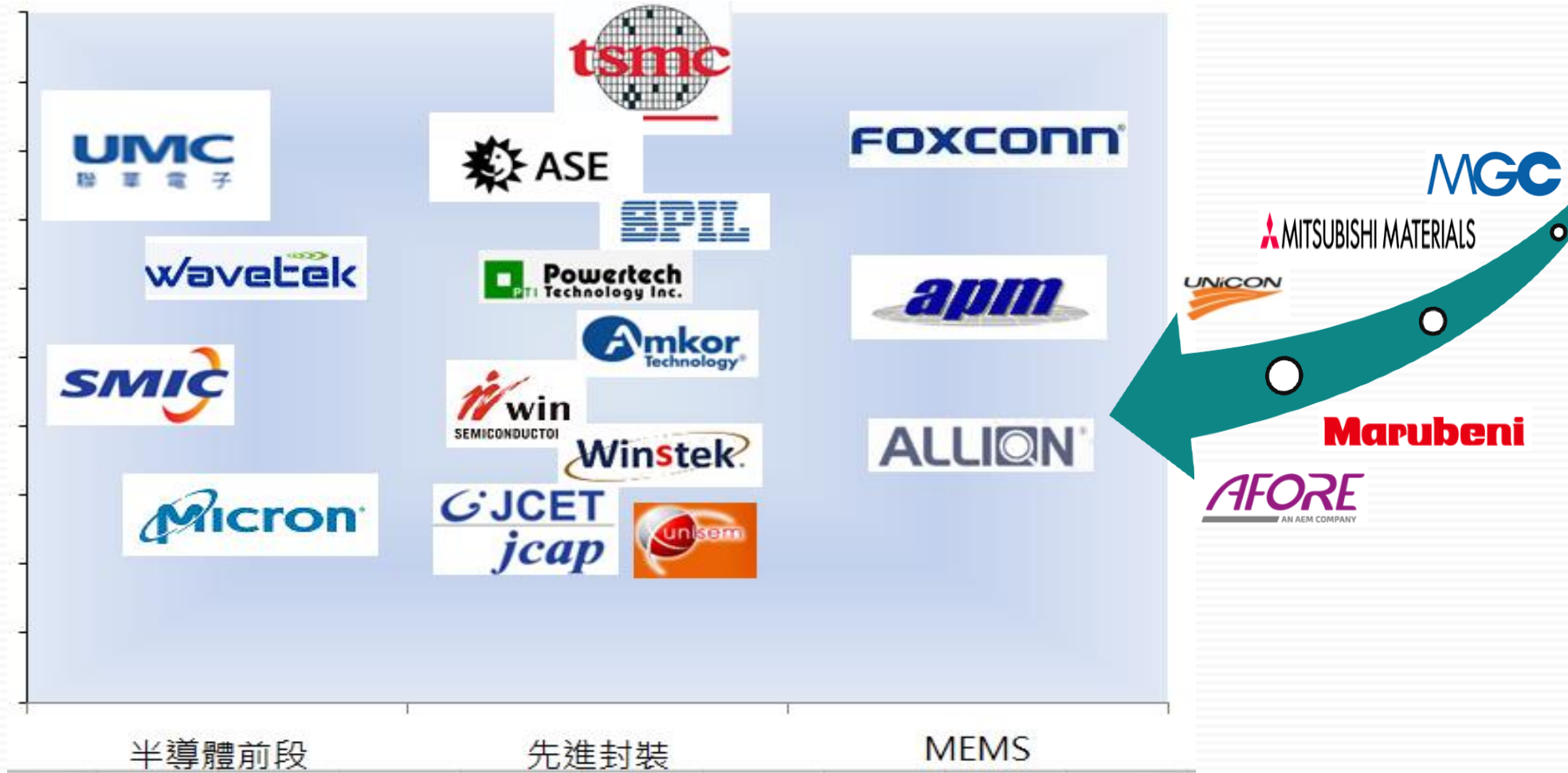


- ✓ Lead frame metal finish chemicals
- ✓ QFN lead frame EDPR
- ✓ High-end fine pitch MLO on probe card

- ✓ MEMS WLO test equipment
- ✓ Test equipment for IMU devices
- ✓ Test equipment for pressure sensors

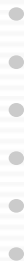


Clients and Partners



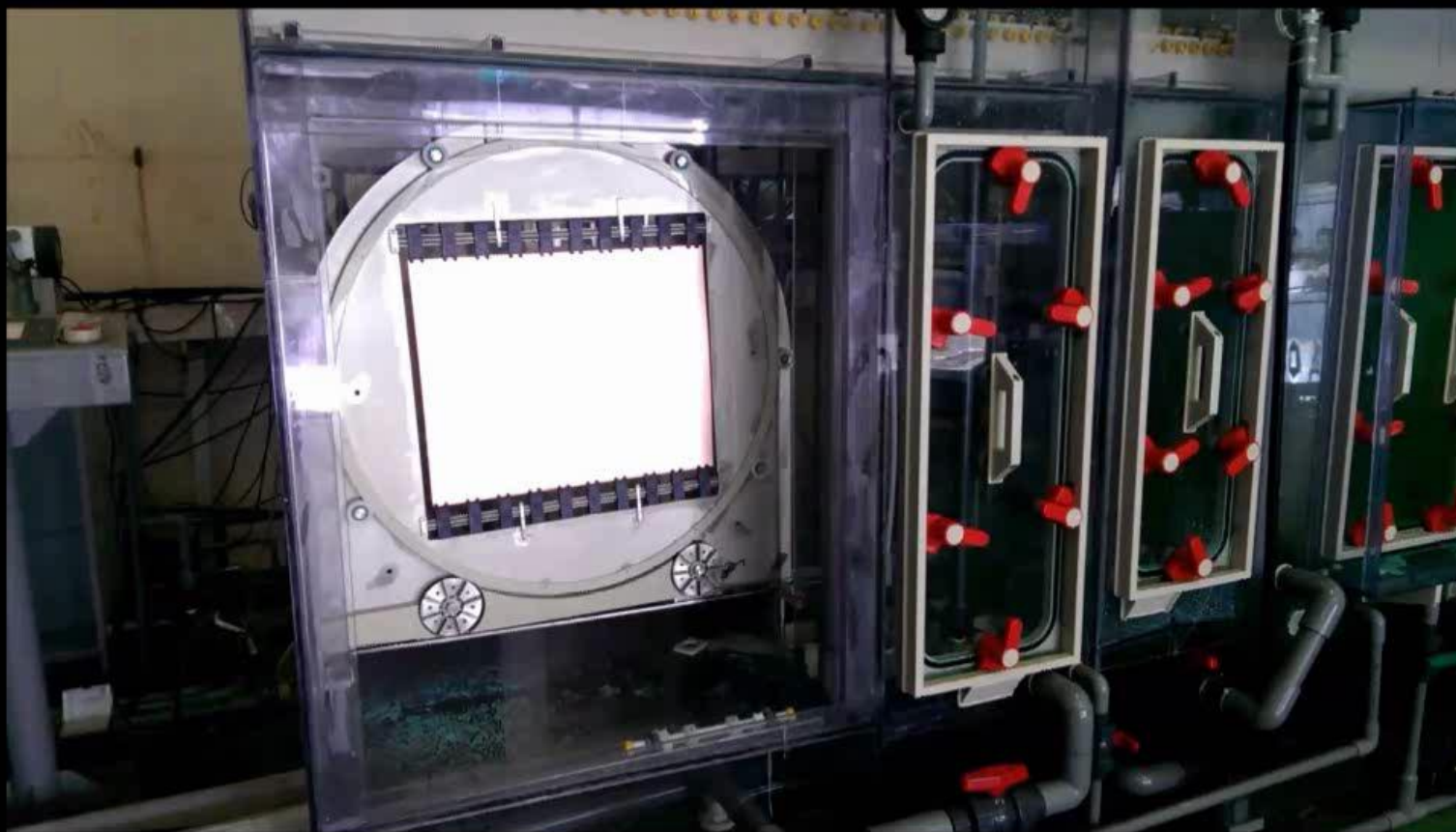


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Products Introduction

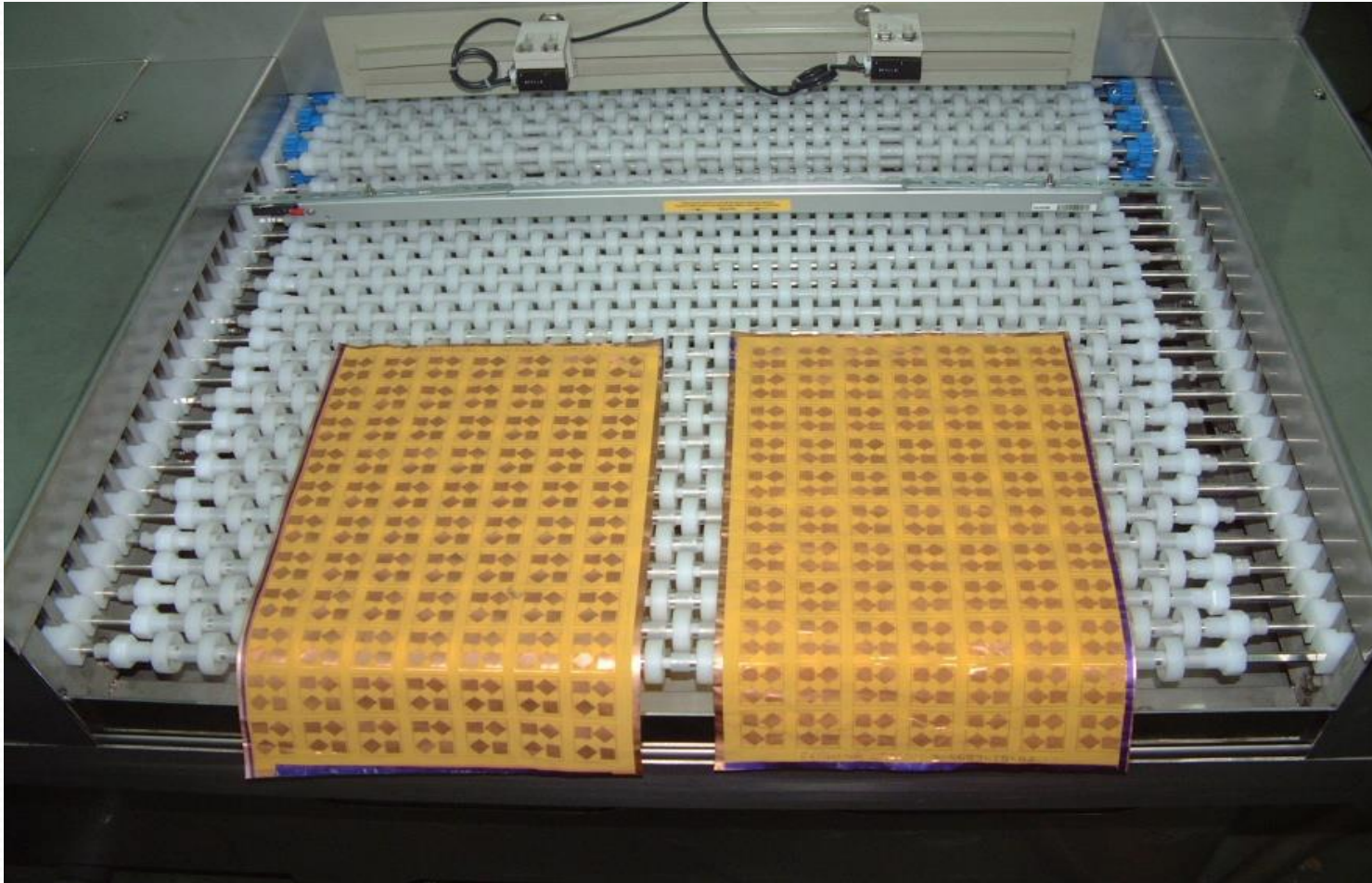






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Conventional Horizontal System : Contact of board surface and roller may cause scratches and contamination

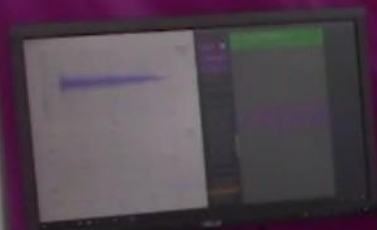




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Meant for MEMS



AFORE

Meant for MEMS





Market in 2018 and Future Outlook

In the treacherous global situation of politics and economy in 2018, it will be the turning point for the global electronic industry.

Compared with present mature technologies, the applications of artificial intelligence and 5G high-speed communications will have a breakthrough in the second half of the year.

Taiwan owns its hardware advantages as well as a complete upstream and downstream supply chain with many years of experience in the electronic industry. Ampoc, with its business philosophy of the electronics industry, continues to actively serve the clients in semiconductor front-end, advanced packaging, and MEMS.



Taiwan PCB industry review 2017 and outlook 2018

- In 2017, the global output value of PCB reached US\$65 billion, the highest level in the past decade.
- 2017 market share of PCB industry (by country):
 - Taiwan 31.3% ↑(30.2%)
 - Japan 20.5% ↓(21.6%)
 - Korea 14.3% ↓(17.6%)
 - China 17.4% ↑(16.8%)
- Taiwan took the top with 30% market share. Japan and South Korea declined with different factors, while China was growing strongly.
- Communication industry and automobile electronics was major momentum in the growth of PCB industry for 2017.
- In 2018, PCB industry is expected to expand the capacity for HDI, soft substrate and rigid- flex board applicable to smart phones, automobile electronics, IoT and Netcom.



Taiwan PCB industry review 2017 and outlook 2018

- 2018 Equipment demand checkpoints :
- 1. The change of smartphone spec will stimulate the demand for HDI, substrate-like PCB and soft substrate production tools.
- 2. Chinese suppliers also join the competition of high-end products, including HDI and soft substrate production tools.
- 3. The increase of applications of automobile electronics will stimulate the demand for related production tools.



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Financial Information





Statement of Comprehensive Income from 2015 to 2017

Unit: NT\$ thousands (Except EPS: NT\$)

Item	Year	2015	2016	2017
Net Revenue		2,200,585	2,312,375	2,281,684
Gross profit		617,928	749,415	677,644
Gross margin(%)		28.08	32.41	29.70
Operating income		305,660	390,622	310,926
Net income after tax		286,899	326,235	247,036
EPS		2.51	2.85	2.16



Balance Sheet from 2015 to 2017

Unit: NT\$ thousands

Item	Year	2015	2016	2017
Current Assets		2,370,950	2,310,668	2,493,281
Non-current Assets		657,258	685,653	752,903
Total Assets		3,028,208	2,996,321	3,246,184
Current Liabilities		748,692	657,291	860,792
Non-current Liabilities		98,100	111,804	130,608
Total Liabilities		846,792	769,095	991,400
Equity		2,181,416	2,227,226	2,254,784



Financial Analysis from 2015 to 2017

Item	Year	2015	2016	2017
Debts Ratio (%)		27.96	25.67	30.54
Current Ratio(%)		316.68	351.54	289.65
Average Inventory Turnover (Times)		2.15	2.37	2.09
Return on Equity (%)		13.07	14.80	11.02



Future outlook

- Business development direction
- Competitive Advantage
- Unfavorable factors and countermeasures



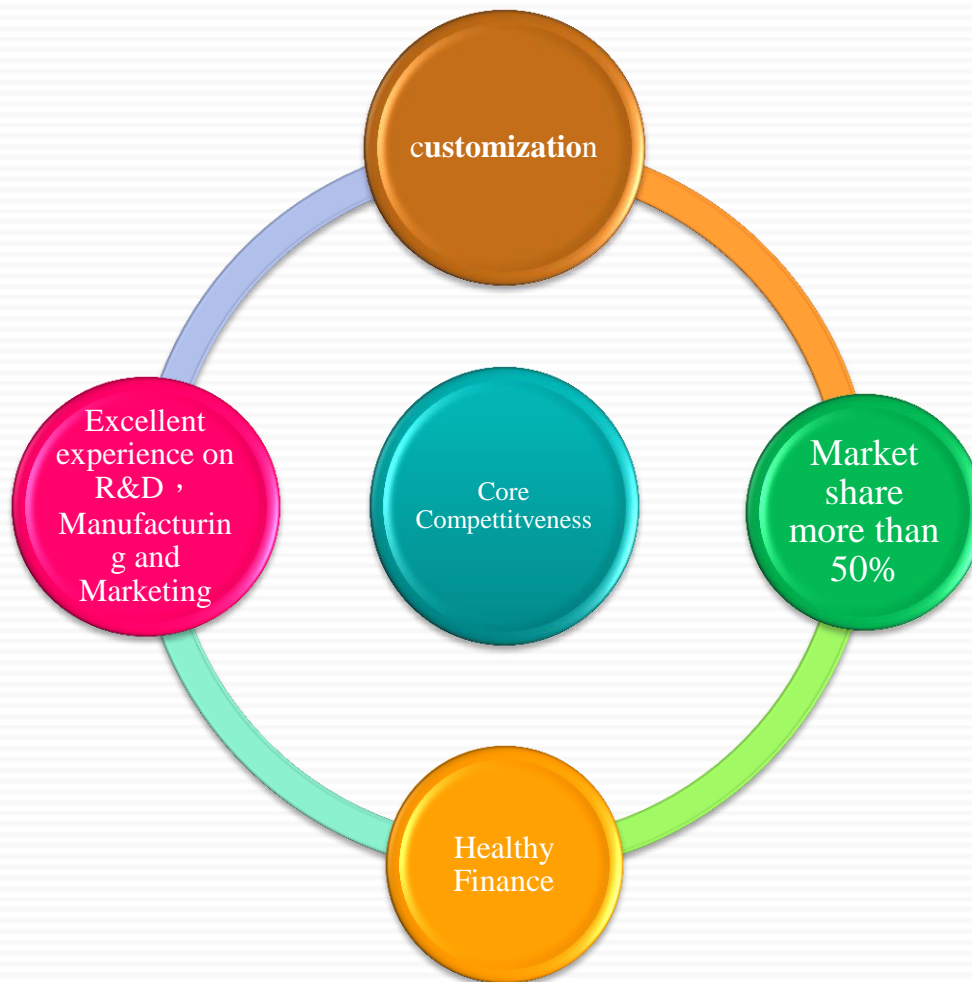


Business development direction

- Developing innovative technology equipment
 - HDI and substrate-like PCB process equipment
 - FPCB and Rigid PCB process equipment
 - Automotive substrate process equipment
 - Intelligent equipment
- Developing new markets
 - Southeast Asia
 - India



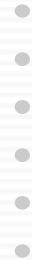
Competitive Advantage





Unfavorable factors and countermeasures

- Low price competition
 - Ampoc is going to keep R&D investment and continue to develop all kinds of new technology equipment to receive our customer's trust and orders.
- Increase of manpower and material
 - Ampoc is going to reduce high price material through widely usage of computer and robot.



Thank you
The End

